

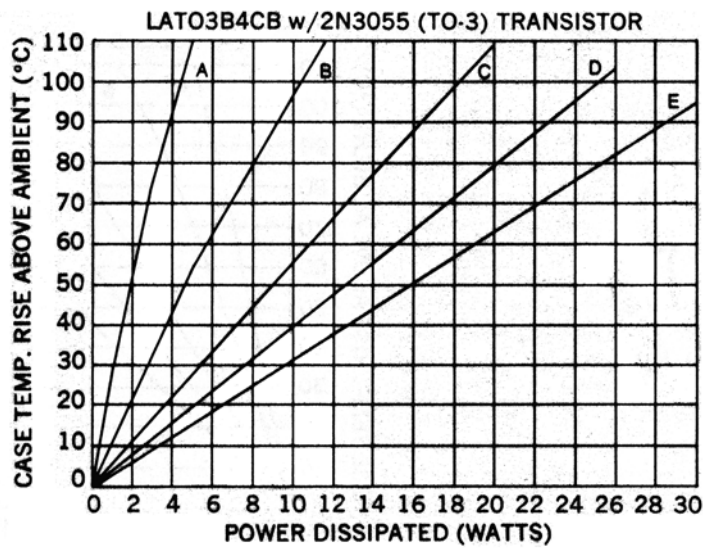
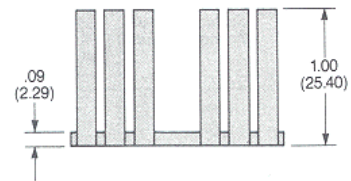
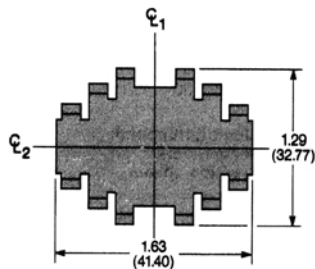
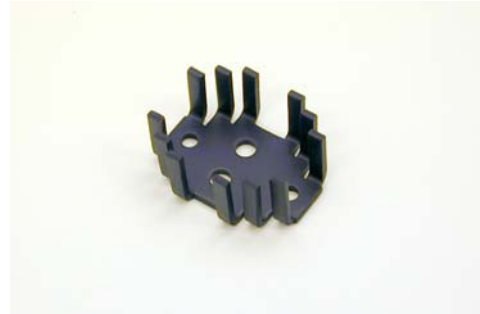
METAL CASE, CASE-MOUNTED SEMICONDUCTORS

Part Number Series LA-B4

Natural Conv. ($^{\circ}\text{C}/\text{W}$): 10.3

Forced Air ($^{\circ}\text{C}/\text{W}$): 3.2

Mounting Envelope: 1.63" x 1.29" x 1.00"



DESCRIPTION OF CURVES

- A. N.C. Horiz. Device Only Mounted to G-10.
- B. N.C Horiz. & Vert. With Dissipator.
- C. 200 FPM w/Diss.
- D. 500 FPM w/Diss.
- E. 1000 FPM w/Diss.

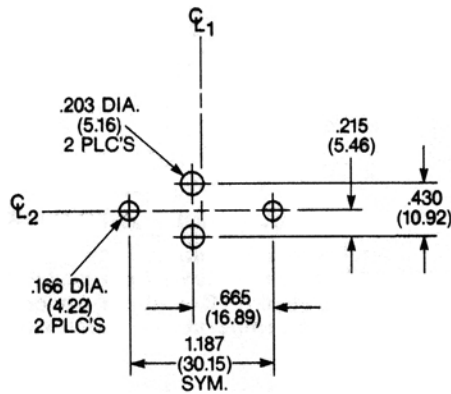
- Thermal Resistance Case to Sink is 0.1-0.3 $^{\circ}\text{C}/\text{W}$ w/Joint Compound.
- Derate 0.7 $^{\circ}\text{C}/\text{watt}$ for unplated part in natural convection only.

Ordering Information

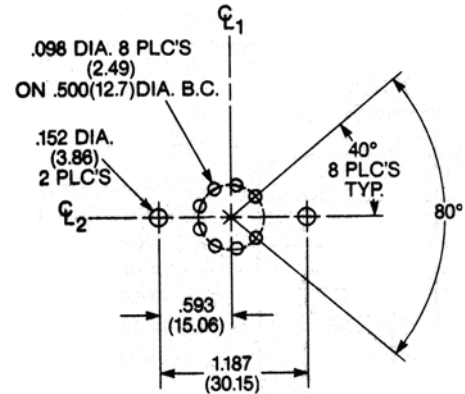
CTS IERC PART NO.			Semiconductor Accommodated	Hole patt. ref. no.	Max. Weight (Grams)
Unplated	Comm'l. Black Anodize	Mil. Black Anodize			
LA000B4U	LA000B4CB	LA000B4B	Undrilled	--	12.9
LAT03B4U	LAT03B4CB	LAT03B4B	TO-3	2	12.9
LAIC3B4U	LAIC3B4CB	LAIC3B4B	TO-3 IC	4	12.9
LA407B4U	LA407B4CB	LA407B4B	TO-3 (4-pin)	5	12.9
LA394B4U	LA394B4CB	LA394B4B	Universal	8	12.9

HOLE PATTERNS

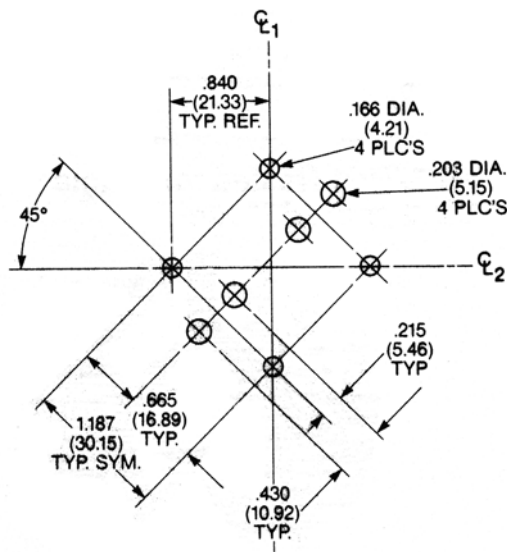
2. Hole Pattern no. 236 accommodates TO-3s. Available in LA-B series heat dissipators only.



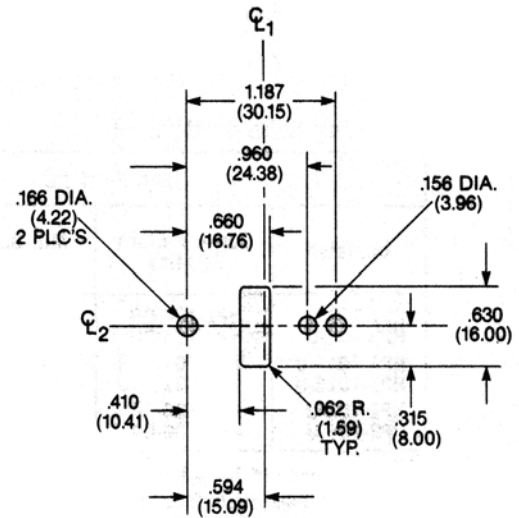
4. Hole pattern no. 237 accommodates To-3 ICs. Available in LA-B series heat dissipators only.



5. Hole pattern no. 407 accommodates TO-3s (4-pin). Available in LA-B series heat dissipators only.



8. Hole pattern no. 394 (universal) accommodates TO-3s, TO-66s, TO-126s, TO-127s, or T-220s. Available in LA-B series heat dissipators only.



CTS IERC, Heat Sinks and Thermal Management Solutions

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